

FPC status

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Line&Space test

- FPC design is constrained by
 - # of signal lines
 - **line&space for signal line**
 - # of LV & HV lines (layers)
- Need to know how narrow line&space can be made.
 - we are discussing with the manufacturer in Korea who has ability to make long FPC
 - We are testing 50, 70, 100um L/S for 130cm FPC (signal layer only) and will check uniformity of the line/space
 - We will visit the manufacture in Nov.



FPC design

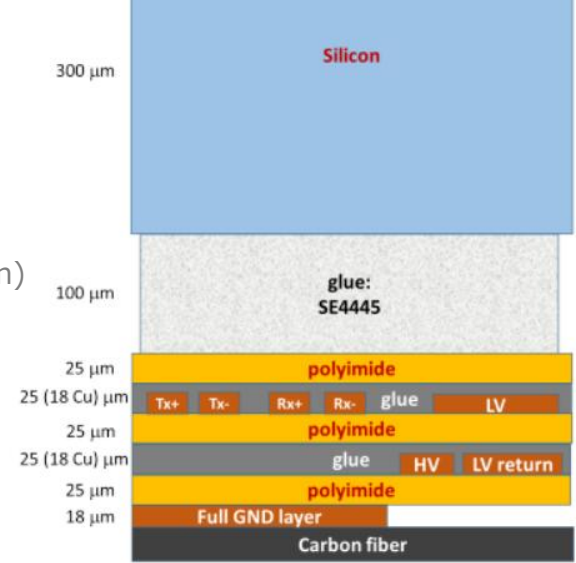
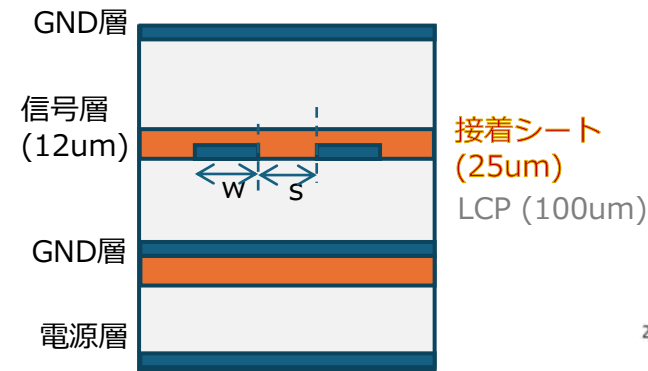
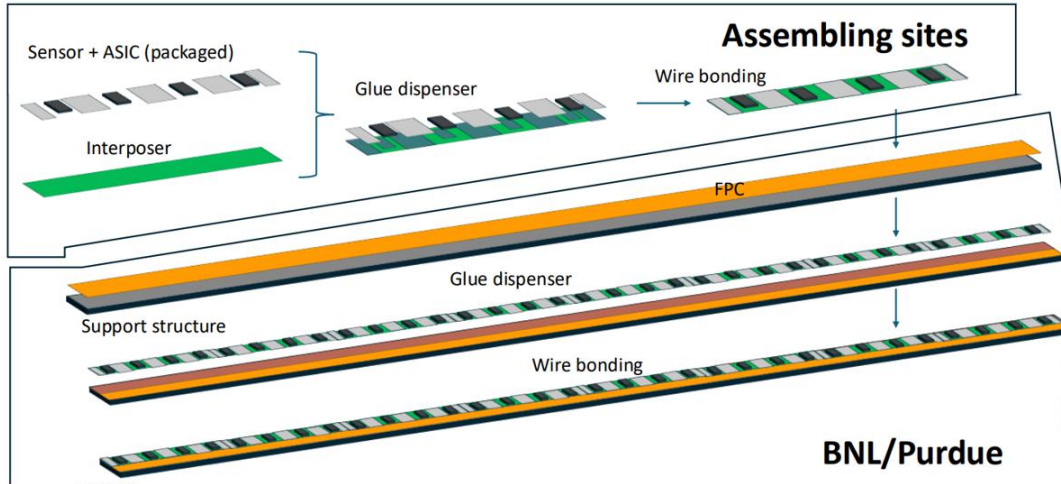
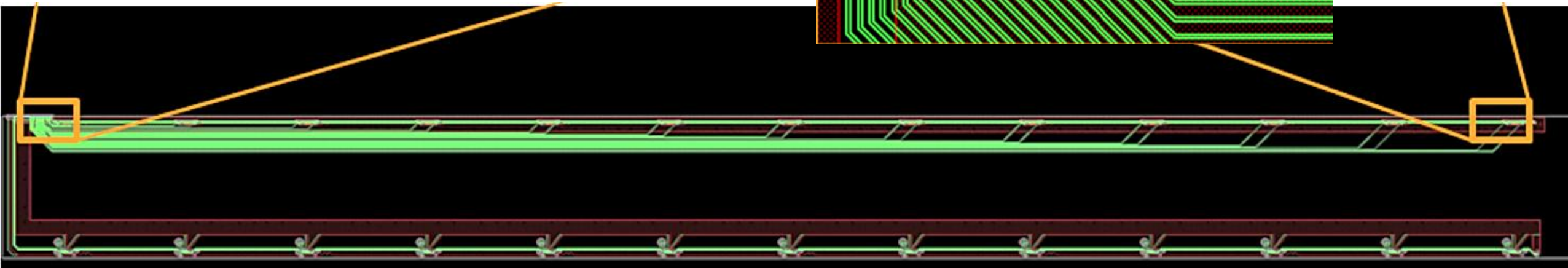
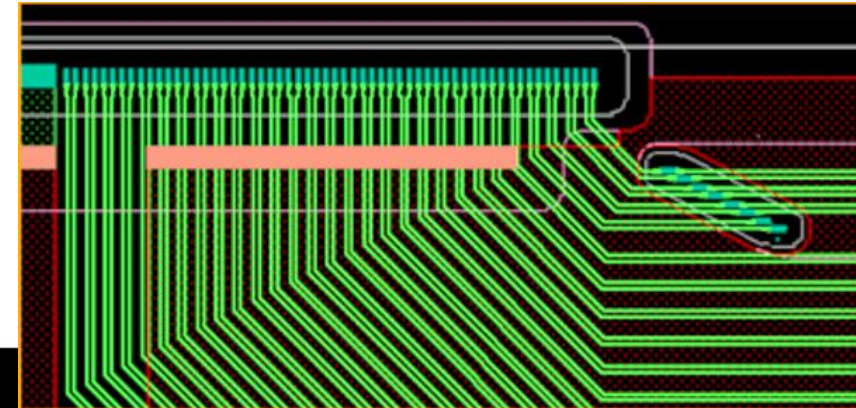


Figure 7. Recommended future bus tape stack-up.

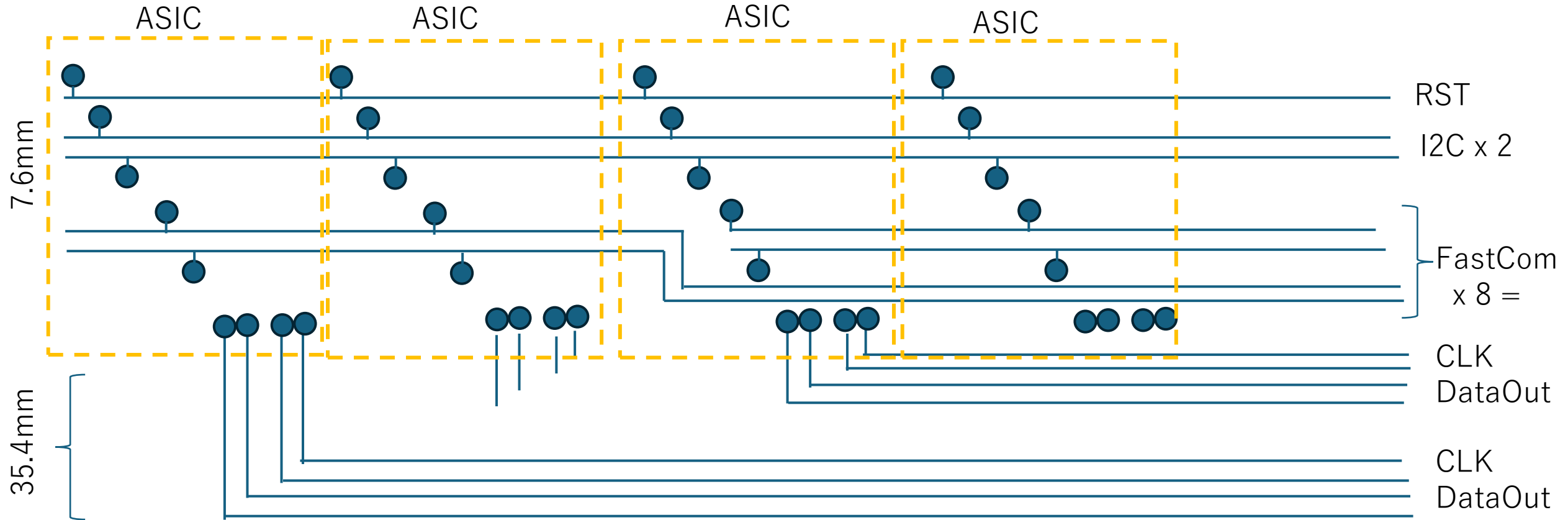
- Consider ITK-FPC like structure
 - Integrate Signal, HV, and LV into a single FPC
- Needs for FPC design
 - Number and width of signal lines, #LV & HV)
 - Microstrip line? Strip line?
 - Strip line offers better signal quality but increases



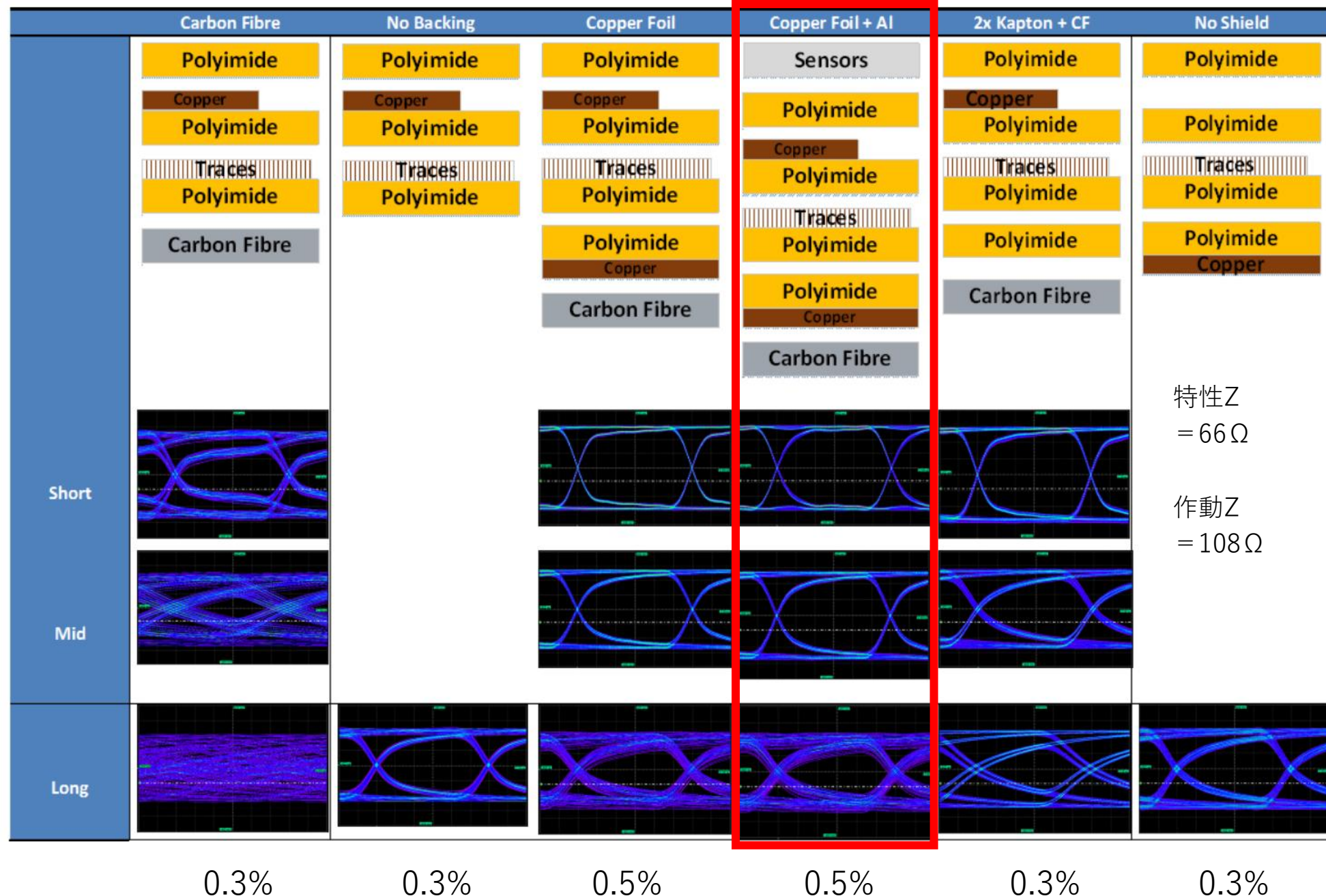
#Signal lines based on ETROC2

- Nsignals:
 - Digital lines:
 - Tx: 1x DataOut (pair = 2lines) -> p2p
 - Rx: CLK40 (pair = 2lines) -> p2p
 - Rx: FastCom (pair = 2lines) -> 4 chips shared
 - Rx: I2C (2 lines, SCK, SDA) -> 16 chip shared
 - Rx: RSTn (1 line) -> all chip shared
 - Rx: I2C addr (5bits)
 - Analog : 1 line (Vtemp) -> p2p
 - 130 cm FPC = 32 ASICs/FPC (x2 FPC x 2cm/sens)
- # of signal lines for 32 ASIC's in a FPC = $32 \times \{2 + 2 + 2/4 + 2/16 + 1/32 + 1\} = 177$
 - -> if assuming the width of signal line = N, $177 \times (N \times 2) = (2 \text{ from line \& space})$
 - if N=100 (70) um, $177 \times 100 \times 2 + 1.3 (\text{ランドや余裕}) = 4.6\text{cm} (3.2\text{cm})$ (5.6cm is maximum width of FPC)
- Power lines : LV(1.8V), GND, HV.
 - There was no quantitative discussion in the past. How many sensor is a HV line shared? One HV line or multiple lines or one for each? Each stavelet? 8 stavelets for one FPC ?

Strawman ideas of routing the signal lines in FPC



- Line arrangement in signal layer : No cross-over of lines allowed
 - Line (N-um) + space (N-um) + Land (for thru hole, $N*2 \sim 4 \text{ um}$)
 - Thru hole width : $\sim 8.8\text{mm}$ ($0.6\text{mm}*7 + 0.52\text{mm}*8 + 0.6\text{mm} = 4.2+4+0.6$)
 - Line area width: $32 * 4 * (2*N\text{-um}) =$
 - Land for powers and GND are also necessary
- $\sim 44.2\text{mm}$: signal lines occupy $< 5\text{cm}$ width



Cu:18um (0.13%)
 PI:25um (0.01%)
 Glue:25um (PIと同じ)
 L/S = 100um

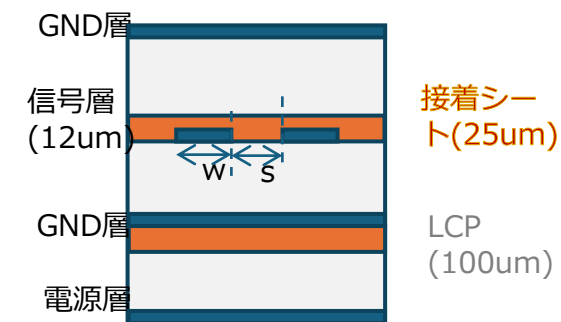
物質量少ない理由

- ・ マイクロストリップ構造
 - ・ 電源、GND層で挟んでいない
- ・ スルーホールがないのでメッキしていない

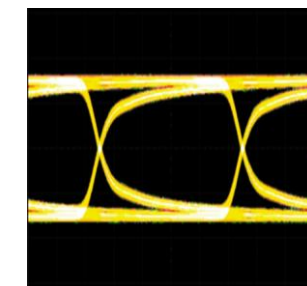
特性Z
 = 66 Ω

作動Z
 = 108 Ω

INTT BEX



4層は接着剤によって張り合わせている



特性Z
 = 47 Ω

作動Z
 = 93 Ω

130cm BEX + FPC(20cm)

Lessons learned in high frequency data transmission design: ATLAS strips bus tape
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